# **Surface Mount Ultrafast Power Rectifier**

### Plastic SOD-123FL Package

This SOD-123FL ultrafast rectifier provides fast switching performance with soft recovery in a compact thermally efficient package. Its compact footprint makes it ideally suited to portable and automotive applications where board space is at a premium. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

#### **Features**

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile Maximum Height of 1.0 mm
- Small Footprint Footprint Area of 5.94 mm<sup>2</sup>
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Mechanical Characteristics:**

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 11.7 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

#### **Applications**

- Instrumentation
- Output Rectification in Switching Power Supplies Including Mini Adapters and Flat Panel Display
- LED Lighting
- Freewheeling Diode Where Space is at a Premium
- Engine Control
- Infotainment and Other Space Constrained Center–stack Applications



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# ULTRAFAST RECTIFIER 2.0 AMPERES 200 VOLTS



SOD-123FL CASE 498 PLASTIC

#### MARKING DIAGRAM



P22 = Specific Device Code

M = Date Code

■ = Pb–Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NHP220SFT3G	SOD-123 (Pb-Free)	10000/Tape & Reel
NRVHP220SFT3G	SOD-123 (Pb-Free)	10000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	200	V
Average Rectified Forward Current (T <sub>L</sub> = 140°C)	I <sub>O</sub>	2.0	Α
Peak Repetitive Forward Current (Square Wave, 20 kHz, T <sub>L</sub> = 135°C)	I <sub>FRM</sub>	4.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	40	Α
Storage and Operating Junction Temperature Range (Note 1)	T <sub>stg</sub> , T <sub>J</sub>	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	$\Psi_{JCL}$	23	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	85	°C/W
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{ heta JA}$	330	°C/W

#### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 4) $ \begin{aligned} (I_F &= 1.0 \text{ A, } T_J = 25^{\circ}\text{C}) \\ (I_F &= 2.0 \text{ A, } T_J = 25^{\circ}\text{C}) \\ (I_F &= 1.0 \text{ A, } T_J = 125^{\circ}\text{C}) \\ (I_F &= 2.0 \text{ A, } T_J = 125^{\circ}\text{C}) \end{aligned} $	V <sub>F</sub>	1.0 1.05 0.86 0.90	V
Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, T <sub>J</sub> = 25°C) (Rated dc Voltage, T <sub>J</sub> = 125°C)	I <sub>R</sub>	0.5 35	μΑ
Reverse Recovery Time I <sub>F</sub> = 2.0 A; $V_R$ = 30 V; dl/dt = 50 A/ $\mu$ s T <sub>J</sub> = -40°C to 150°C	t <sub>rr</sub>	50	ns

<sup>2.</sup> Mounted with 700 mm<sup>2</sup> copper pad size (Approximately 1 in<sup>2</sup>) 1 oz FR4 Board.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board.
 Pulse Test: Pulse Width ≤ 380 μs, Duty Cycle ≤ 2.0%.

#### TYPICAL CHARACTERISTICS

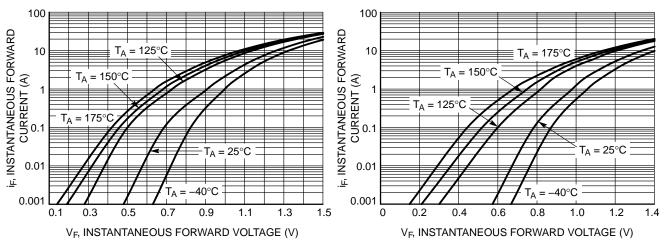


Figure 1. Typical Instantaneous Forward Characteristics

Figure 2. Maximum Instantaneous Forward Characteristics

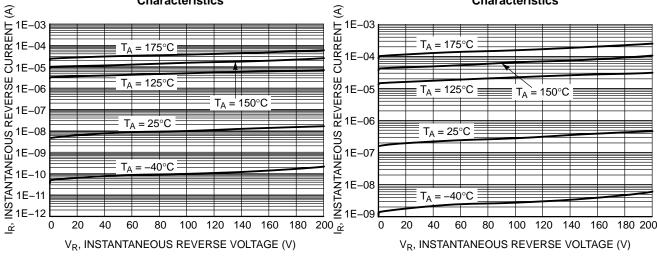


Figure 3. Typical Reverse Characteristics

Figure 4. Maximum Reverse Characteristics

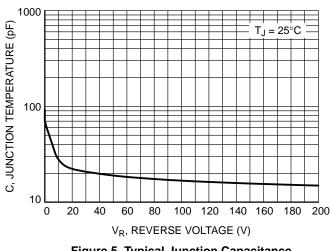


Figure 5. Typical Junction Capacitance

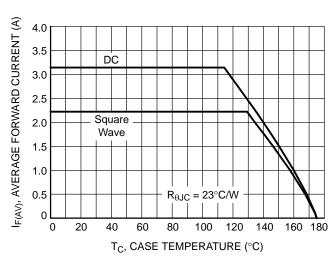


Figure 6. Current Derating

#### **TYPICAL CHARACTERISTICS**

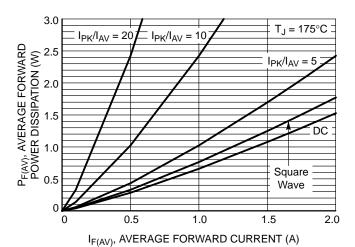


Figure 7. Forward Power Dissipation

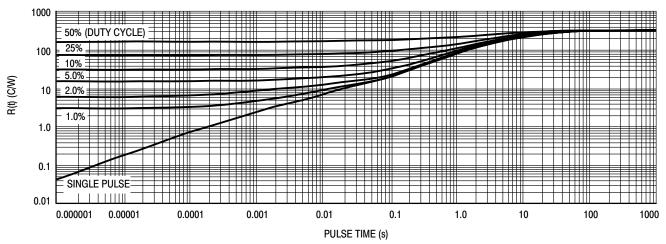


Figure 8. Thermal Response, Junction-to-Ambient (20 mm<sup>2</sup> pad)

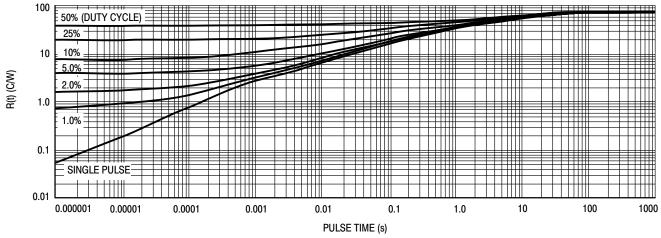
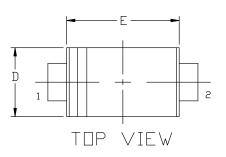


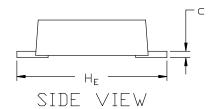
Figure 9. Thermal Response, Junction-to-Ambient (1 in<sup>2</sup> pad)

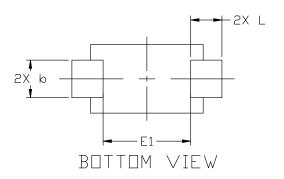


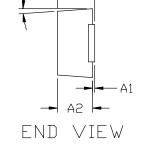
#### SOD-123-2 1.65x2.70x0.90 CASE 498 ISSUE E

#### DATE 22 AUG 2023





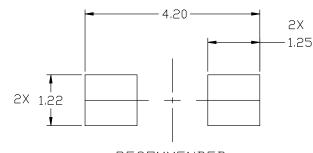




	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.90	0.95	0.98
A1	0.00	0.05	0.10
A2	0.85	0.90	0.95
b	0.70	0.90	1.10
U	0.10	0.15	0.20
D	1.50	1.65	1.80
E	2.50	2.70	2.90
E1	1.70	2.10	2.50
HE	3.40	3.60	3.80
L	0.55	0.75	0.95
θ	0°		8°

#### NOTES:

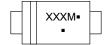
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS 6 AND L ARE TO BE MEASURED ON A FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH PROTRUSIONS, OR GATE BURRS.
- 5. FLAT LEAD.



## RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the IIN Semiconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

## GENERIC MARKING DIAGRAM\*



XXX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOD-123-2 1.65x2.70x0.90	)	PAGE 1 OF 1

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